NOTE

1. MATERIAL
   1.1 MJ HOUSING: PBT, WITH 30% GF, UL94V-0, COLOR: SEE TABLE
   1.2 MJ CONTACTS: PHOSPHOR BRONZE
   1.3 MJ SHEILD: BRASS
   1.4 USB HOUSING: PBT, UL94V-0, COLOR: SEE TABLE
   1.5 USB CONTACTS: BRASS
   1.6 USB SHEILD: SPCC

2. FINISH
   2.1 MJ CONTACTS: GOLD FLASH PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAILS
   1.25 µm (50µ]) MIN. NICKEL UNPLATED OVERALL
   2.2 MJ SHEILD: 0.508µm (20µ) MIN. NICKEL PLATED
   2.3 USB CONTACTS: GOLD FLASH PLATED ON CONTACT AREA, 2.55µm [100µ] MIN. NICKEL UNPLATED ON SOLDER TAILS, 1.25 µm [50µ] MIN. NICKEL UNPLATED OVERALL
   2.4 USB SHEILD: 2.032µm [80µ] MIN. NICKEL PLATED

3. WAVE SOLDER CAPABLE TO 265°C PER TE CONNECTIVITY SPEC.

MATERIALS: PBT GR 9011 FLX 50%, UL94V-0, PHOSPHOR BRONZE, BRASS, SPCC

RECOMMENDED PCB LAYOUT
RECOMMENDED PCB THICKNESS: 1.6mm
TOLERANCE: ±0.05 (TOP VIEW)

TE Connectivity Ltd.